


## Amendments To The Claims

Please enter the following amendments.

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1. (Original) A method for testing wire bonds in an integrated circuit package, comprising:  
bonding an integrated circuit silicon die to a package substrate;  
forming a wire connection between a circuit contact pad in said integrated circuit silicon die and a lead contact pad in said package substrate; and  
testing said wire connection for detection of non-stick failure with a testing device, wherein the silicon substrate of said integrated circuit provides electrical continuity for said non-stick detection between said circuit contact pad and a dedicated contact pad in said package substrate which is electrically coupled to said testing device.
  2. (Original) A method as described in Claim 1, wherein said bonding said integrated circuit die to a package substrate is performed using conductive epoxy.
  3. (Original) A method as described in Claim 1, wherein said bonding said integrated circuit die to said package substrate is performed using non-conductive epoxy.
  4. (Amended) A method as described in Claim 1, wherein ~~each~~ of said lead contact pads in said package substrate is ~~are~~ electrically isolated from other lead contact pads in said package substrate.
  5. (Amended) A method as described in Claim 1, wherein said bonding said integrated circuit silicon die provides electrical continuity between said integrated circuit silicon die and said dedicated pad[s] in said package substrate.
  6. (Amended) A method as described in Claim 1, wherein said testing of said wire connections-for non stick failure comprises testing said wire connection for continuity through a circuit contact pad on said integrated circuit die and a dedicated contact pad in said packaging substrate.
  7. (Original) A method as described in Claim 1, wherein said testing of said wire connections for non stick failure comprises testing said wire connection for a short through said lead contact pad on said packaging substrate.

8. (Original) A method as described in Claim 1, wherein said method is performed recursively for a plurality of said wire connections.

CLAIMS 9 – 24 (Cancelled).

25. (New) A method for recursively testing a plurality of wire bonds in an integrated circuit package, comprising:

bonding an integrated circuit die to a package substrate;  
forming connections between a plurality of circuit contact pads in said integrated circuit silicon die and a plurality of lead contact pads in said package substrate; and  
testing said connections for detection of non-stick failure with a testing device, wherein the substrate of said integrated circuit provides electrical continuity for said non-stick detection between said circuit contact pads and a predetermined contact pad in said package substrate which is coupled to said testing device.

26. (New) A method as described in Claim 25, wherein said bonding said integrated circuit die to a package substrate is performed using conductive epoxy.

27. (New) A method as described in Claim 25, wherein said bonding said integrated circuit die to said package substrate is performed using non-conductive epoxy.

28. (New) A method as described in Claim 25, wherein said lead contact pads in said package substrate are electrically isolated from other lead contact pads in said package substrate.

29. (New) A method as described in Claim 25, wherein said bonding said integrated circuit die provides electrical continuity between said integrated circuit die and said predetermined pad in said package substrate.

30. (New) A method as described in Claim 25, wherein said testing of said connections for non stick failure comprises testing each of said wire connections for continuity through a circuit contact pad on said integrated circuit die and said predetermined contact pad in said packaging substrate.

31. (New) A method as described in Claim 25, wherein said testing of said connections for non stick failure comprises testing each of said connections for a short through said lead contact pad on said packaging substrate.

32. (New) A method for recursively testing a plurality of wire bonds in an integrated circuit package, comprising:

bonding an integrated circuit die to a package substrate;

forming connections between a plurality of circuit contact pads in said integrated circuit silicon die and a plurality of lead contact pads in said package substrate; and

testing said connections for detection of non-stick failure with a testing device, wherein the substrate of said integrated circuit provides electrical continuity for said non-stick detection between said circuit contact pads and a predetermined contact pad in said package substrate which is coupled to said testing device and wherein each of said lead contact pads in said package substrate is electrically isolated from other lead contact pads in said package substrate.

33. (New) A method as described in Claim 32, wherein said bonding said integrated circuit die to a package substrate is performed using conductive epoxy.

34. (New) A method as described in Claim 32, wherein said bonding said integrated circuit die to said package substrate is performed using non-conductive epoxy.

35. (New) A method as described in Claim 32, wherein said bonding said integrated circuit silicon die provides electrical continuity between said integrated circuit die and said predetermined pad in said package substrate.

36. (New) A method as described in Claim 32, wherein said testing of said connections for non stick failure comprises testing said connections for continuity through a circuit contact pad on said integrated circuit die and said predetermined contact pad in said packaging substrate.

37. (New) A method as described in Claim 32, wherein said testing of said connections for non stick failure comprises testing each of said connections for a short through said lead contact pads on said packaging substrate.